

## Product Change Notification / CAAN-22NDYJ154

## Date:

24-Nov-2022

## **Product Category:**

Inductive Position Sensors

## PCN Type:

Manufacturing Change

## **Notification Subject:**

CCB 5398 Initial Notice: Qualification of Microchip Technology Tempe – Fab 2 as an additional fab site for selected LX3302A and LX34050 device families available in 14L TSSOP (4.4mm) package.

## Affected CPNs:

CAAN-22NDYJ154\_Affected\_CPN\_11242022.pdf CAAN-22NDYJ154\_Affected\_CPN\_11242022.csv

## Notification Text:

PCN Status:Initial Notification

PCN Type: Manufacturing Change

**Microchip Parts Affected:**Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change**: Qualification of Microchip Technology Tempe – Fab 2 as an additional fab site for selected LX3302A and LX34050 device families available in 14L TSSOP (4.4mm) package.

#### Pre and Post Change Summary:

Pre Change	Post Change

Fab Site	XFAB Silicon Foundries (Malaysia)	XFAB Silicon Foundries (Malaysia)	Microchip Technology Tempe – Fab 2 (TMGR)
	(XFML)	(XFML)	

#### Impacts to Data Sheet:None

#### Change ImpactNone

**Reason for Change:**To improve manufacturability by qualifying Microchip Technology Tempe – Fab 2 (TGMR) as an additional fab location.

#### Change Implementation Status: In Progress

#### Estimated Qualification Completion Date:September 2023 (2339)

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

#### Time Table Summary:

	November 2022				^	September 2023				23	
Workweek	4 5	4 6	4 7	4 8	4 9		3 5	3 6	3 7	3 8	3 9
Initial PCN Issue Date				х							
Qual Report Availability											х
Final PCN Issue Date											х

#### Method to Identify Change:Traceability code

**Qualification Plan:**Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Plan.

Revision History: November 24, 2022: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## Attachments:

## PCN\_CAAN-22NDYJ154\_Qual Plan.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

#### **Terms and Conditions:**

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our PCN home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the PCN FAQ section.

If you wish to <u>change your PCN profile, including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections. CAAN-22NDYJ154 - CCB 5398 Initial Notice: Qualification of Microchip Technology Tempe – Fab 2 as an additional fab site for selected LX3302A and LX34050 device families available in 14L TSSOP (4.4mm) package.

Affected Catalog Part Numbers (CPN)

LX3302AQPW-EASY LX3302AQPW LX3302AQPW-TR-EASY LX3302AQPW-TR LX34050QPW LX34050QPW-VAO LX34050QPW-TR LX34050QPW-TR-VAO LX3302AQPW-TR-C01



# **QUALIFICATION PLAN SUMMARY**

## PCN#: CAAN-22NDYJ154

Date: November 17, 2022

Qualification of Microchip Technology Tempe – Fab 2 as an additional fab site for selected LX3302A and LX34050 device families available in 14L TSSOP (4.4mm) package. **Purpose:** Qualification of Microchip Technology Tempe – Fab 2 as an additional fab site for selected LX3302A and LX34050 device families available in 14L TSSOP (4.4mm) package.

**CCB:** 5398

Test Name	Conditions	Sample Size	Qty of Lots	Total Units	
Preconditioning	MSL-1/260°C	231	3	738	
Freconditioning	M3E-1/200 C	231	5	730	
HAST	+130°C/85% RH for 96 hours or +110C/85%RH/264HRS	77	3	246	
UHAST	+130°C/85% RH for 96 hours or +110C/85%RH/264HRS	77	3	246	
Temp Cycle	-65°C to +150°C for 500 cycles or -55C to +150C for 1000cyc	77	3	246	
HTSL	@175°C for 1008HRS	45	1	45	
HTOL	@150°C for 1008HRS	77	3	246	
EDR (endurance retention)	@150°C for 1008HRS	77	3	246	
ELFR	@150°C for 48HRS	800	3	2400	
ESD/HBM	Pre / Post ATE at Room, Hot; *include ±250V, ±500V, ±1kV, and ±2kV	12	1	12	
ESD/CDM	Pre / Post ATE at Room, Hot; include ±250V, ±500V and ±750V on all pins	12	1	12	
Latch Up	Pre / Post ATE at Room, Hot	12	1	12	
Electrical Distributions	ATE at Room, Hot, Cold	30	3	90	
LTDR (low temp data retention)	25°C , ATE Room, Hot	77	3	246	